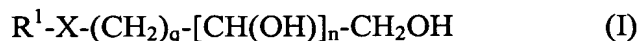


AMENDMENTS TO THE CLAIMS

Claim 1 (Original): A polishing liquid composition for polishing a surface to be polished comprising an insulating layer and a metal layer, the polishing liquid composition comprising a compound having a structure in which each of two or more adjacent carbon atoms has a hydroxyl group in a molecule, and water, wherein the compound having a structure in which each of two or more adjacent carbon atoms has a hydroxyl group in a molecule is represented by the formula (I):



wherein

$R^1$  is a hydrocarbon group having 1 to 24 carbon atoms;

X is a group represented by

$(CH_2)_m$ , wherein m is 1,

oxygen atom,

sulfur atom,

COO group,

OCO group,

a group represented by  $NR^2$  or

$O(R^2O)P(O)O$ , wherein  $R^2$  is hydrogen atom or a hydrocarbon group having 1

to 24 carbon atoms;

q is 0 or 1; and

n is an integer of 1 to 4.

Claim 2 (Original): The polishing liquid composition according to claim 1, further comprising an organic acid.

Claim 3 (Original): The polishing liquid composition according to claim 2, wherein the organic acid is an etching agent.

Claim 4 (Original): The polishing liquid composition according to claim 1, further comprising an etching agent comprising an inorganic acid.

Claim 5 (Currently Amended): A polishing liquid composition for polishing a surface to be polished comprising an insulating layer and a metal layer, the polishing liquid composition comprising an aliphatic carboxylic acid having 7 to 24 10 carbon atoms and/or a salt thereof, an etching agent comprising an organic acid, and water, wherein the organic acid of the etching agent is at least one selected from the group consisting of

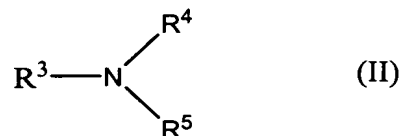
- A: aliphatic organic acids having 6 or less carbon atoms and one to three carboxyl groups;
- B: aromatic organic acids having 7 to 10 carbon atoms and one to four carboxyl groups;
- C: organic acids having 6 or less carbon atoms and one to four phosphonic groups; and
- D: polyaminocarboxylic acids having in a molecule two or more structures represented by the formula (III):



wherein the metal layer includes copper or copper alloys.

Claim 6 (Previously Presented): A polishing liquid composition for polishing a surface to be polished comprising an insulating layer and a metal layer, the polishing liquid composition comprising

an amine compound represented by the following general formula (II):



wherein

$\text{R}^3$  is a linear or branched alkyl group having 4 to 18 carbon atoms,  
a linear or branched alkenyl group having 4 to 18 carbon atoms,  
an aryl group having 6 to 18 carbon atoms, and  
an aralkyl group having 7 to 18 carbon atoms;

each of  $\text{R}^4$  and  $\text{R}^5$ , which may be identical or different, is  
a linear alkyl group having 1 to 8 carbon atoms or  
a branched alkyl group having 3 to 8 carbon atoms, or  
a group represented by  $\text{H}-(\text{OR}^6)_Z$ , wherein  $\text{R}^6$  is a linear alkylene

group having 1 to 3 carbon atoms, or

a branched alkylene group having 3 carbon atoms; and

$Z$  is a number of 1 to 20, and/or a salt thereof,

an etching agent,

an oxidizing agent, and

water.

Claim 7 (Previously Presented): The polishing liquid composition according to Claim 1, further comprising an oxidizing agent, an abrasive or a mixture thereof.

Claim 8 (Canceled)

Claim 9 (Withdrawn): A method of using a polishing liquid composition, the method comprising polishing a surface using the polishing liquid composition of Claim 1.

Claim 10 (Canceled)

Claim 11 (Previously Presented): The polishing liquid composition according to claim 2, further comprising an oxidizing agent, an abrasive or a mixture thereof.

Claim 12 (Previously Presented): The polishing liquid composition according to claim 5, further comprising an oxidizing agent, an abrasive or a mixture thereof.

Claim 13 (Previously Presented): The polishing liquid composition according to claim 6, further comprising an oxidizing agent, an abrasive or a mixture thereof.

Claim 14 (Withdrawn): A method of using a polishing liquid composition, the method comprising polishing a surface using the polishing liquid composition of claim 2.

Claim 15 (Withdrawn): A method of using a polishing liquid composition, the method comprising polishing a surface using the polishing liquid composition of claim 5.

Claim 16 (Withdrawn): A method of using a polishing liquid composition, the method comprising polishing a surface using the polishing liquid composition of claim 6.

Claim 17 (Withdrawn): A method of using a polishing liquid composition, the method comprising polishing a surface using the polishing liquid composition of claim 7.

Claim 18 (Withdrawn ): A method of using a polishing liquid composition, the method comprising polishing a surface using the polishing liquid composition of claim 11.

Claim 19 (Withdrawn): A method of using a polishing liquid composition, the method comprising polishing a surface using the polishing liquid composition of claim 12.

Claim 20 (Withdrawn): A method of using a polishing liquid composition, the method comprising polishing a surface using the polishing liquid composition of claim 13.

Claims 21-27 (Canceled)

Claim 28 (Withdrawn): A method of making a polishing liquid composition, the method comprising  
mixing water and a compound having a molecular structure in which each of two or more adjacent carbon atoms has a hydroxyl group; and  
producing the polishing liquid composition of claim 1.

Claim 29 (Currently Amended) A method of making a polishing liquid composition, the method comprising  
mixing an aliphatic carboxylic acid having 7 to ~~24~~ 10 carbon atoms and/or a salt thereof, an etching agent, an oxidizing agent and water; and  
producing the polishing liquid composition of claim 5.

Claim 30 (Withdrawn): A method of making a polishing liquid composition, the method comprising

mixing an amine compound, an etching agent, an oxidizing agent and water; and producing the polishing liquid composition of claim 6.

Claims 31-32 (Canceled)

Claims 33-37 (Not Entered)

Claim 38 (New): A polishing liquid composition for polishing a surface to be polished comprising an insulating layer and a metal layer, the polishing liquid composition comprising an aliphatic carboxylic acid having 7 to 24 carbon atoms and/or a salt thereof, an etching agent comprising an organic acid, and water, wherein

the organic acid of the etching agent is at least one selected from the group consisting of

- A: aliphatic organic acids selected from the group consisting of formic acid, propionic acid, tricarballic acid, 2-hydroxypropionic acid, gluconic acid, and amino acids;
- B: aromatic organic acids having 7 to 10 carbon atoms and one to four carboxyl groups; and
- D: polyaminocarboxylic acids having in a molecule two or more structures represented by the formula (III):



Claim 39 (New): The polishing liquid composition according to claim 38, further comprising an oxidizing agent, an abrasive or a mixture thereof.

Claim 40 (New): A method of using a polishing liquid composition, the method comprising polishing a surface using the polishing liquid composition of claim 38.

Claim 41 (New): A method of using a polishing liquid composition, the method comprising polishing a surface using the polishing liquid composition of claim 39.

Claim 42 (New) A method of making a polishing liquid composition, the method comprising

mixing an aliphatic carboxylic acid having 7 to 24 carbon atoms and/or a salt thereof, an etching agent, an oxidizing agent and water; and  
producing the polishing liquid composition of claim 38.